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PD - 96115B

International **IR** Rectifier

- Advanced Process Technology
- Ultra Low On-Resistance
- Dual N and P Channel MOSFET
- Surface Mount
- Available in Tape & Reel
- 150°C Operating Temperature
- Lead-Free

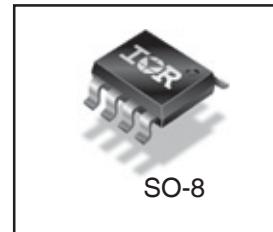
IRF9952QPbF HEXFET® Power MOSFET

	N-Ch	P-Ch
V_{DSS}	30V	-30V
$R_{DS(on)}$	0.10Ω	0.25Ω

Description

These HEXFET® Power MOSFET's in a Dual SO-8 package utilize the lastest processing techniques to achieve extremely low on-resistance per silicon area. Additional features of these HEXFET Power MOSFET's are a 150°C junction operating temperature, fast switching speed and improved repetitive avalanche rating. These benefits combine to make this design an extremely efficient and reliable device for use in a wide variety of applications.

The efficient SO-8 package provides enhanced thermal characteristics and dual MOSFET die capability making it ideal in a variety of power applications. This dual, surface mount SO-8 can dramatically reduce board space and is also available in Tape & Reel.



Base part number	Orderable part number	Package Type	Standard Pack		EOL Notice	Replacement Part Number
			Form	Quantity		
IRF9952QPbF	IRF9952QTRPbF	SO-8	Tape and Reel	4000	EOL 529	Please search the EOL part number on IR's website for guidance
	IRF9952QPbF	SO-8	Tube	95	EOL 529	

		Symbol	Maximum		Units
			N-Channel	P-Channel	
Drain-Source Voltage		V_{DS}	30		V
Gate-Source Voltage		V_{GS}	± 20		
Continuous Drain Current ^⑤	$T_A = 25^\circ\text{C}$	I_D	3.5	-2.3	A
	$T_A = 70^\circ\text{C}$		2.8	-1.8	
Pulsed Drain Current		I_{DM}	16	-10	
Continuous Source Current (Diode Conduction)		I_S	1.7	-1.3	
Maximum Power Dissipation ⑤	$T_A = 25^\circ\text{C}$	P_D	2.0		W
	$T_A = 70^\circ\text{C}$		1.3		
Single Pulse Avalanche Energy		E_{AS}	44	57	mJ
Avalanche Current		I_{AR}	2.0	-1.3	A
Repetitive Avalanche Energy		E_{AR}	0.25		mJ
Peak Diode Recovery dv/dt ②		dv/dt	5.0	-5.0	V/ns
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to + 150		°C

Thermal Resistance Ratings

Parameter	Symbol	Limit	Units
Maximum Junction-to-Ambient ⑥	$R_{θJA}$	62.5	°C/W

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Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter		Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	N-Ch	30	—	—	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
		P-Ch	-30	—	—		$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	N-Ch	—	0.015	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = 1\text{mA}$
		P-Ch	—	0.015	—		Reference to 25°C , $I_D = -1\text{mA}$
$R_{DS(\text{ON})}$	Static Drain-to-Source On-Resistance	N-Ch	—	0.08	0.10	Ω	$V_{GS} = 10\text{V}, I_D = 2.2\text{A}$ ④
		—	—	0.12	0.15		$V_{GS} = 4.5\text{V}, I_D = 1.0\text{A}$ ④
		—	—	0.165	0.250		$V_{GS} = -10\text{V}, I_D = -1.0\text{A}$ ④
		P-Ch	—	0.290	0.400		$V_{GS} = -4.5\text{V}, I_D = -0.50\text{A}$ ④
$V_{GS(\text{th})}$	Gate Threshold Voltage	N-Ch	1.0	—	—	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
		P-Ch	-1.0	—	—		$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$
g_{fs}	Forward Transconductance	N-Ch	—	12	—	S	$V_{DS} = 15\text{V}, I_D = 3.5\text{A}$ ④
		P-Ch	—	2.4	—		$V_{DS} = -15\text{V}, I_D = -2.3\text{A}$ ④
I_{DSS}	Drain-to-Source Leakage Current	N-Ch	—	—	2.0	μA	$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$
		P-Ch	—	—	-2.0		$V_{DS} = -24\text{V}, V_{GS} = 0\text{V}$
		N-Ch	—	—	25		$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$
		P-Ch	—	—	-25		$V_{DS} = -24\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	N-P	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}$
Q_g	Total Gate Charge	N-Ch	—	6.9	14	nC	N-Channel
		P-Ch	—	6.1	12		$I_D = 1.8\text{A}, V_{DS} = 10\text{V}, V_{GS} = 10\text{V}$ ④
Q_{gs}	Gate-to-Source Charge	N-Ch	—	1.0	2.0		P-Channel
		P-Ch	—	1.7	3.4		$I_D = -2.3\text{A}, V_{DS} = -10\text{V}, V_{GS} = -10\text{V}$
Q_{gd}	Gate-to-Drain ("Miller") Charge	N-Ch	—	1.8	3.5	nC	
		P-Ch	—	1.1	2.2		
$t_{d(on)}$	Turn-On Delay Time	N-Ch	—	6.2	12	ns	N-Channel
		P-Ch	—	9.7	19		$V_{DD} = 10\text{V}, I_D = 1.0\text{A}, R_G = 6.0\Omega, R_D = 10\Omega$ ④
t_r	Rise Time	N-Ch	—	8.8	18	ns	
		P-Ch	—	14	28		
$t_{d(off)}$	Turn-Off Delay Time	N-Ch	—	13	26	ns	P-Channel
		P-Ch	—	20	40		$V_{DD} = -10\text{V}, I_D = -1.0\text{A}, R_G = 6.0\Omega, R_D = 10\Omega$
t_f	Fall Time	N-Ch	—	3.0	6.0	ns	
		P-Ch	—	6.9	14		
C_{iss}	Input Capacitance	N-Ch	—	190	—	pF	N-Channel
		P-Ch	—	190	—		$V_{GS} = 0\text{V}, V_{DS} = 15\text{V}, f = 1.0\text{MHz}$
C_{oss}	Output Capacitance	N-Ch	—	120	—	pF	P-Channel
		P-Ch	—	110	—		$V_{GS} = 0\text{V}, V_{DS} = -15\text{V}, f = 1.0\text{MHz}$
C_{rss}	Reverse Transfer Capacitance	N-Ch	—	61	—		
		P-Ch	—	54	—		

Source-Drain Ratings and Characteristics

	Parameter		Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	N-Ch	—	—	1.7	A	
		P-Ch	—	—	-1.3		
I_{SM}	Pulsed Source Current (Body Diode) ④	N-Ch	—	—	16	A	
		P-Ch	—	—	16		
V_{SD}	Diode Forward Voltage	N-Ch	—	0.82	1.2	V	$T_J = 25^\circ\text{C}, I_S = 1.25\text{A}, V_{GS} = 0\text{V}$ ④
		P-Ch	—	-0.82	-1.2		$T_J = 25^\circ\text{C}, I_S = -1.25\text{A}, V_{GS} = 0\text{V}$ ④
t_{rr}	Reverse Recovery Time	N-Ch	—	27	53	ns	N-Channel
		P-Ch	—	27	54		$T_J = 25^\circ\text{C}, I_F = 1.25\text{A}, di/dt = 100\text{A}/\mu\text{s}$ ④
Q_{rr}	Reverse Recovery Charge	N-Ch	—	28	57	nC	P-Channel
		P-Ch	—	31	62		$T_J = 25^\circ\text{C}, I_F = -1.25\text{A}, di/dt = 100\text{A}/\mu\text{s}$ ④

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 23)
- ② N-Channel $I_{SD} \leq 2.0\text{A}$, $di/dt \leq 100\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 150^\circ\text{C}$
P-Channel $I_{SD} \leq -1.3\text{A}$, $di/dt \leq 84\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 150^\circ\text{C}$
- ③ N-Channel Starting $T_J = 25^\circ\text{C}$, $L = 22\text{mH}$ $R_G = 25\Omega$, $I_{AS} = 2.0\text{A}$. (See Figure 12)
P-Channel Starting $T_J = 25^\circ\text{C}$, $L = 67\text{mH}$ $R_G = 25\Omega$, $I_{AS} = -1.3\text{A}$.
- ④ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.
- ⑤ Surface mounted on FR-4 board, $t \leq 10\text{sec}$.

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N-Channel

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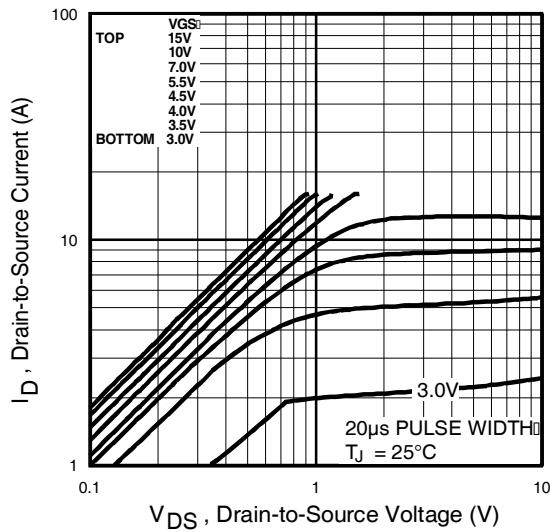


Fig 1. Typical Output Characteristics

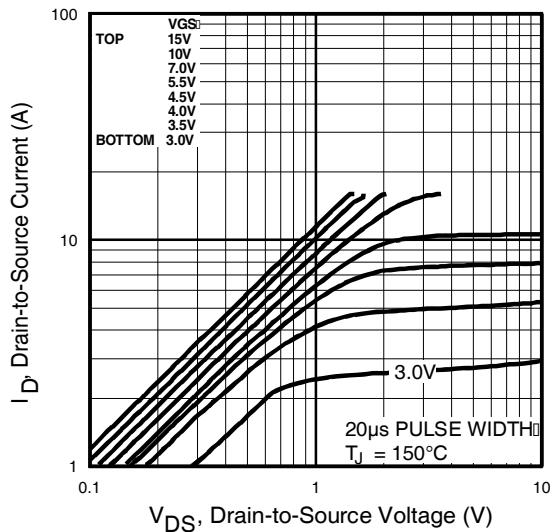


Fig 2. Typical Output Characteristics

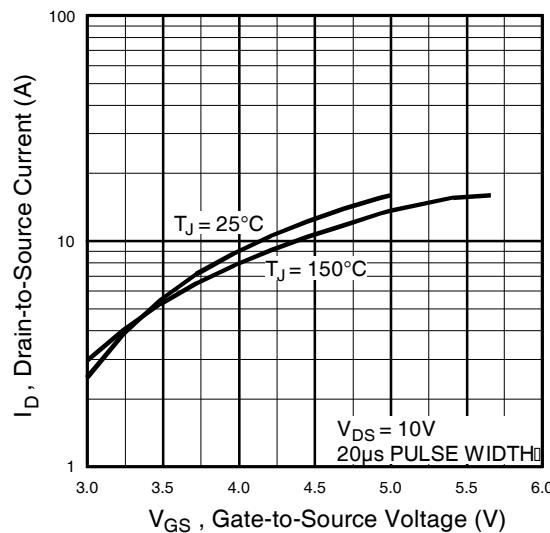


Fig 3. Typical Transfer Characteristics

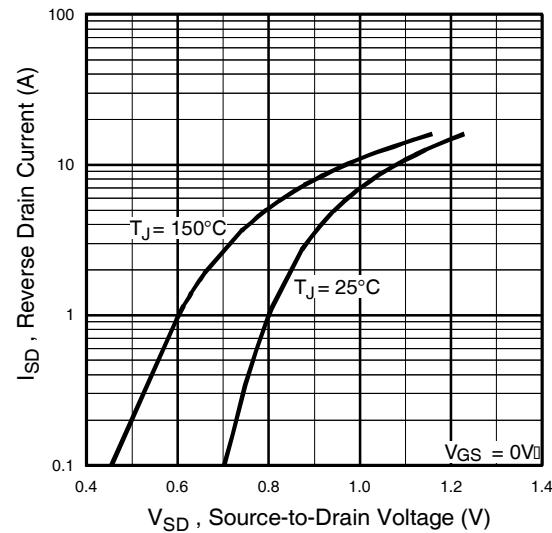


Fig 4. Typical Source-Drain Diode Forward Voltage

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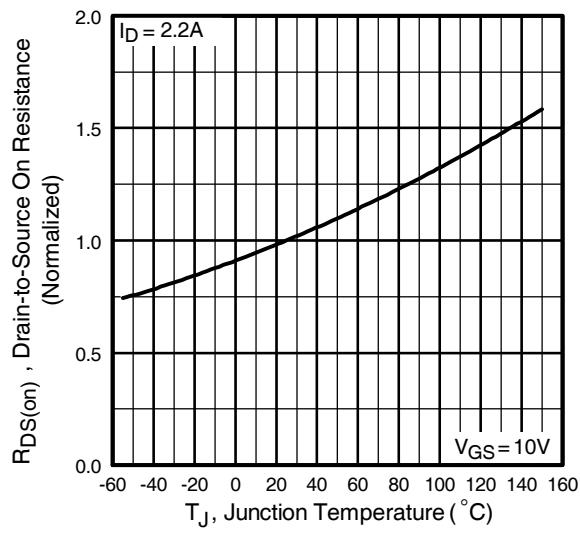


Fig 5. Normalized On-Resistance Vs. Temperature

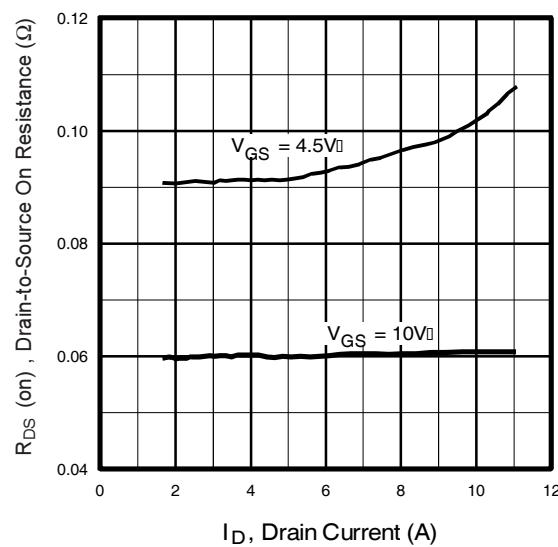


Fig 6. Typical On-Resistance Vs. Drain Current

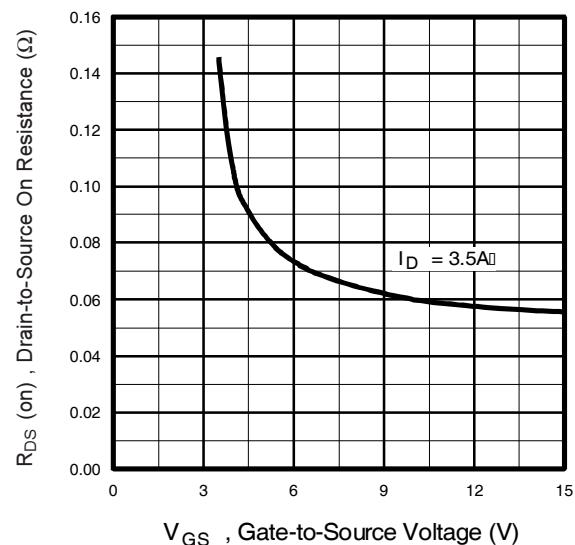


Fig 7. Typical On-Resistance Vs. Gate Voltage

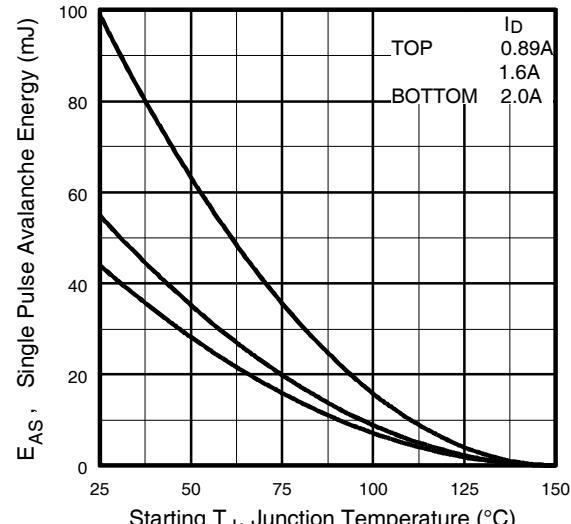
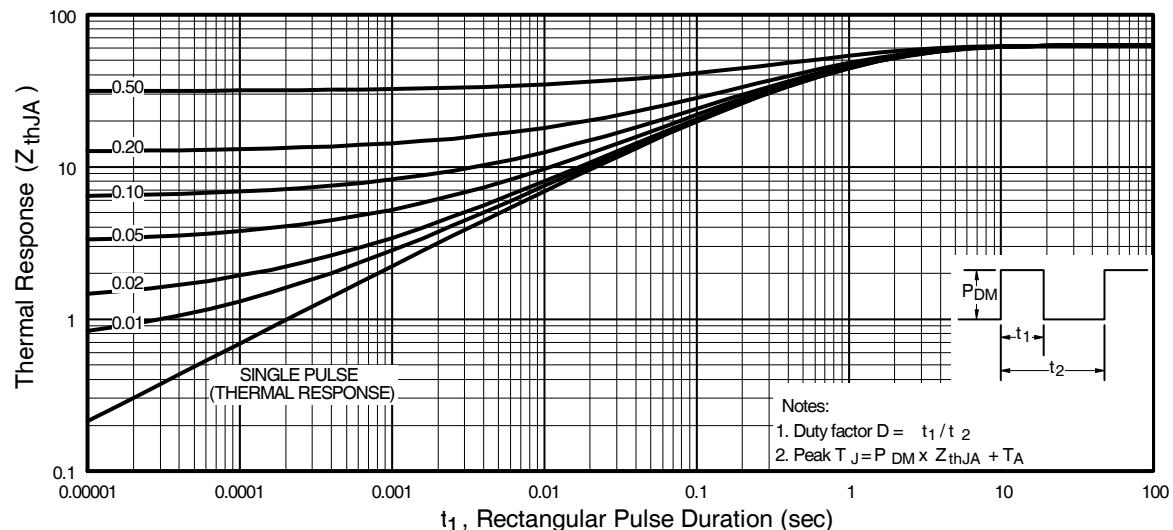
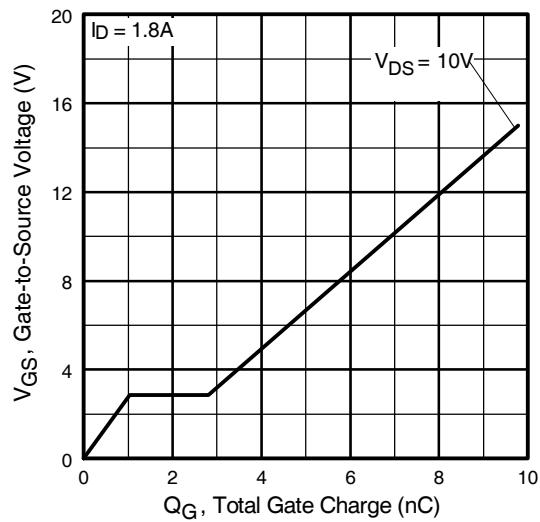
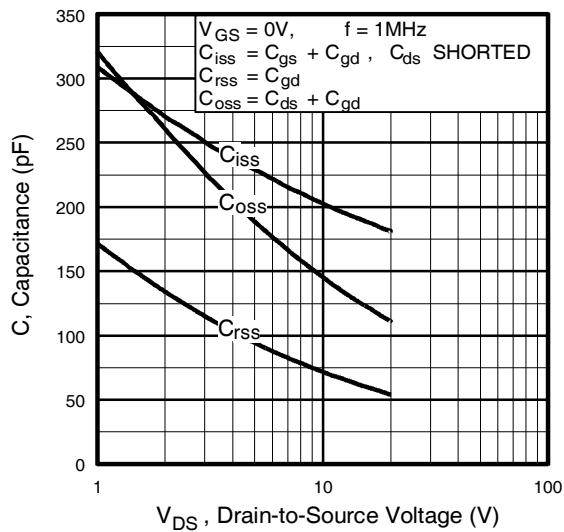


Fig 8. Maximum Avalanche Energy Vs. Drain Current

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P-Channel

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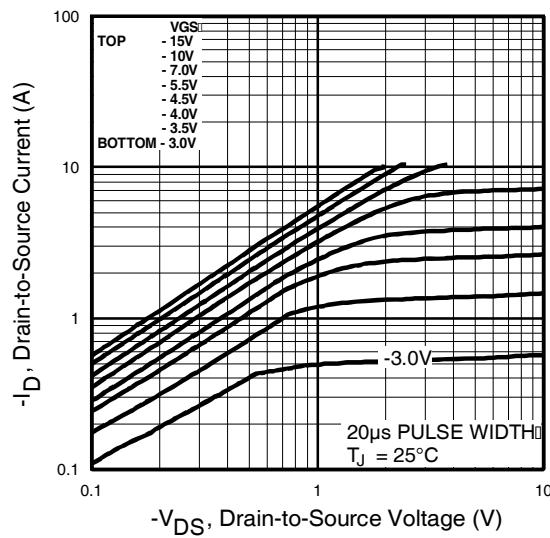


Fig 12. Typical Output Characteristics

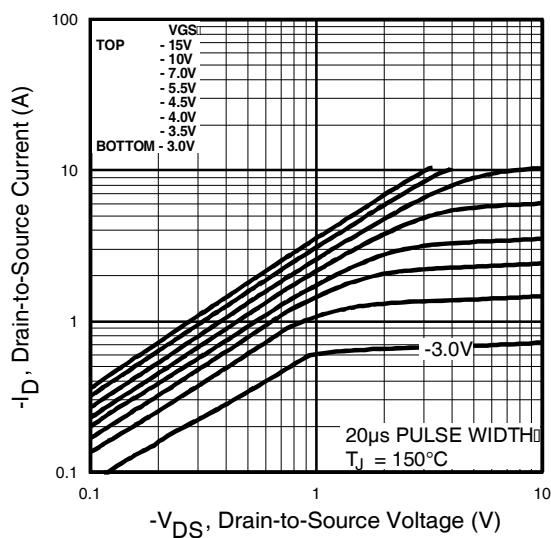


Fig 13. Typical Output Characteristics

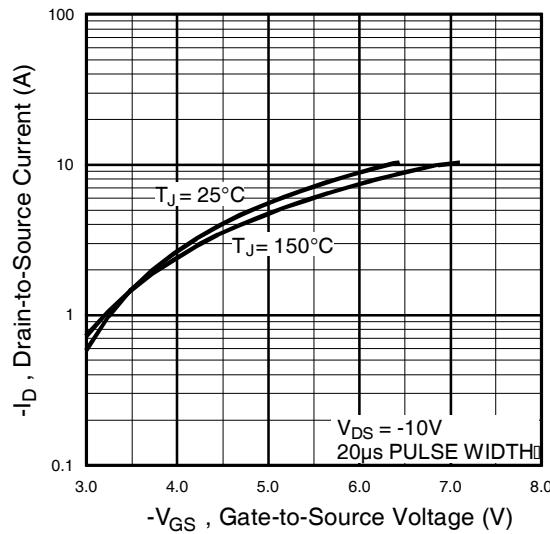


Fig 14. Typical Transfer Characteristics

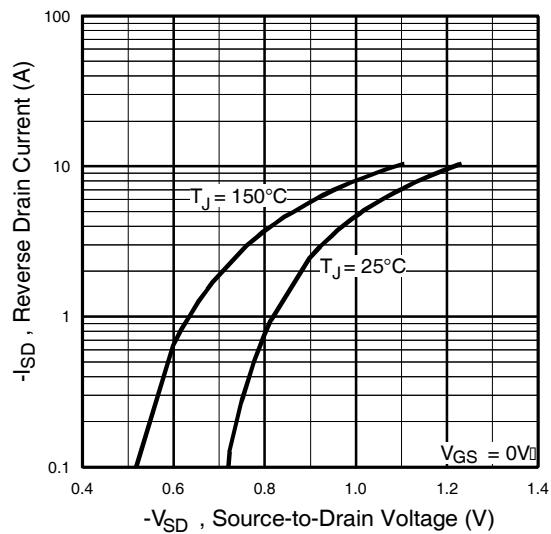


Fig 15. Typical Source-Drain Diode Forward Voltage

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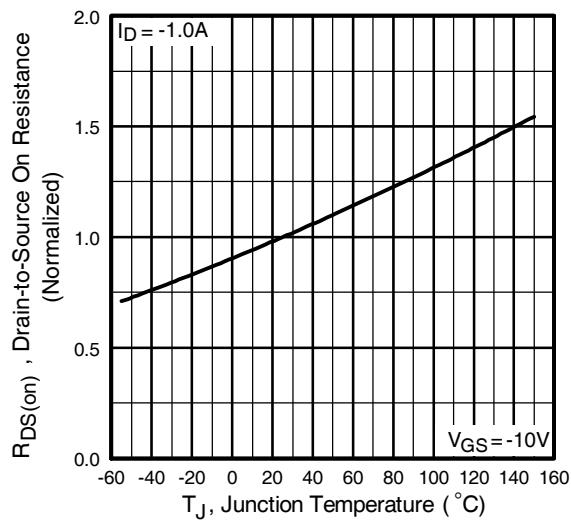


Fig 16. Normalized On-Resistance Vs. Temperature

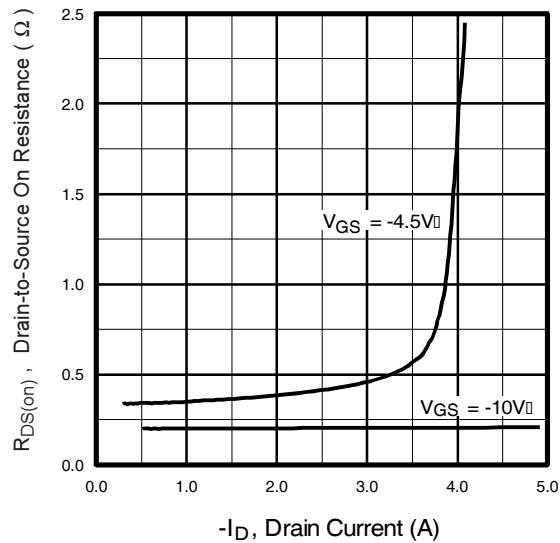


Fig 17. Typical On-Resistance Vs. Drain Current

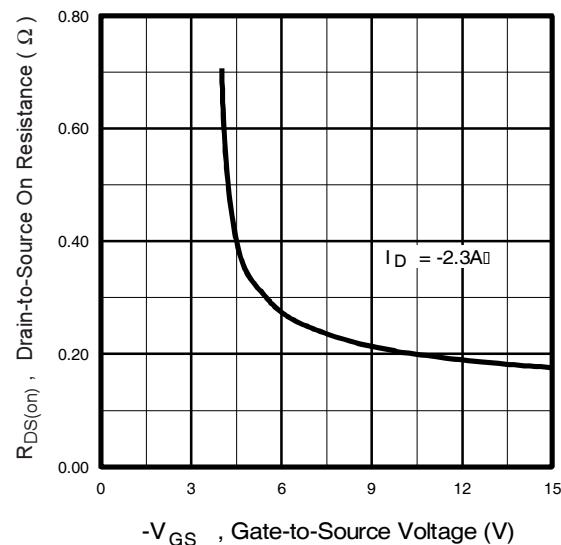


Fig 18. Typical On-Resistance Vs. Gate Voltage

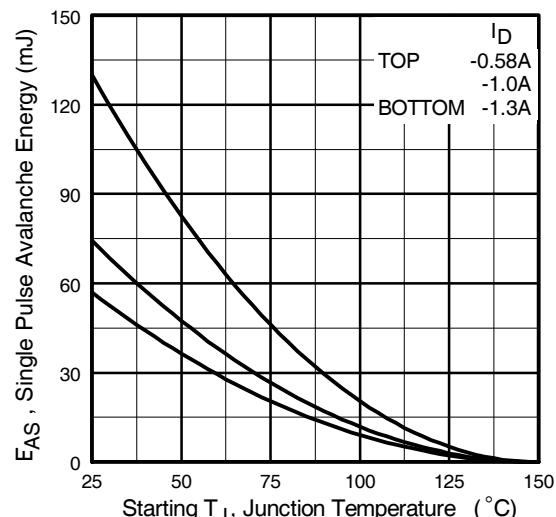


Fig 19. Maximum Avalanche Energy Vs. Drain Current

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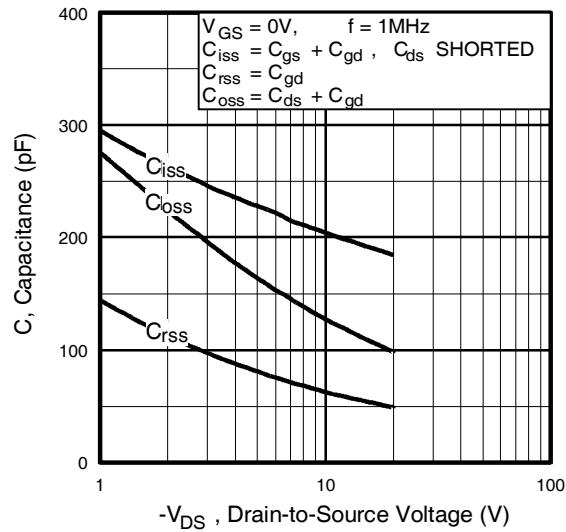


Fig 20. Typical Capacitance Vs.
Drain-to-Source Voltage

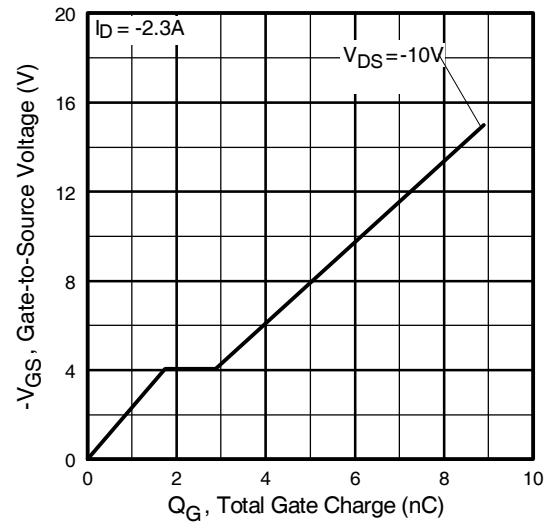


Fig 21. Typical Gate Charge Vs.
Gate-to-Source Voltage

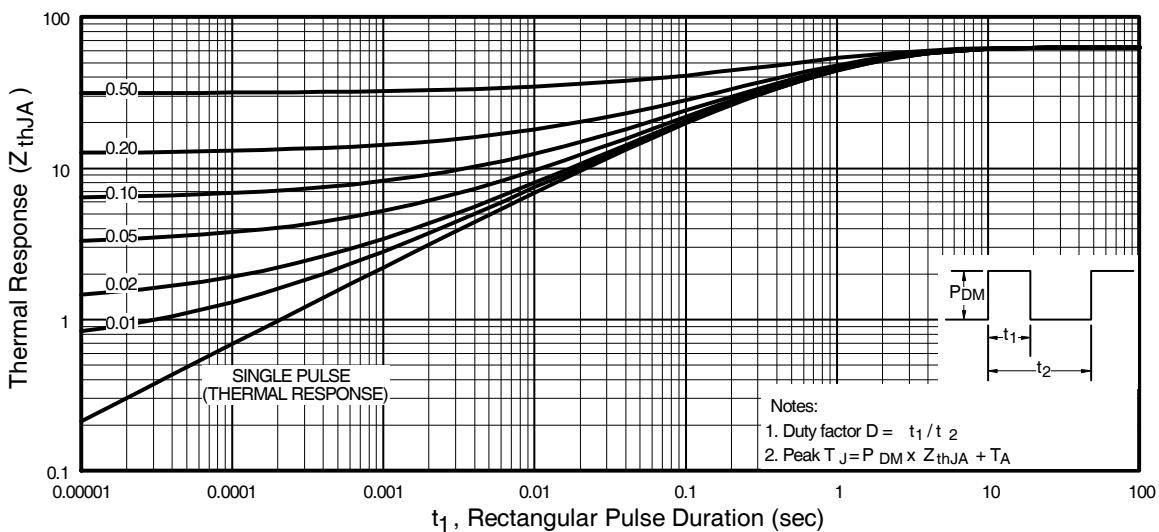


Fig 22. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient
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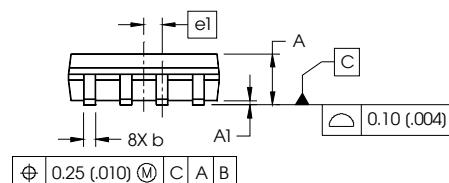
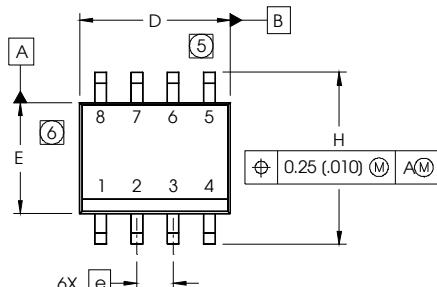
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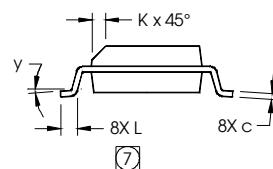
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SO-8 Package Outline

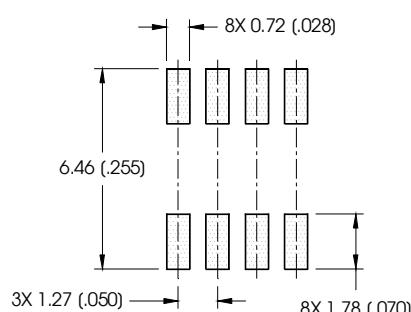
Dimensions are shown in millimeters (inches)



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050	BASIC	1.27	BASIC
e1	.025	BASIC	0.635	BASIC
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°

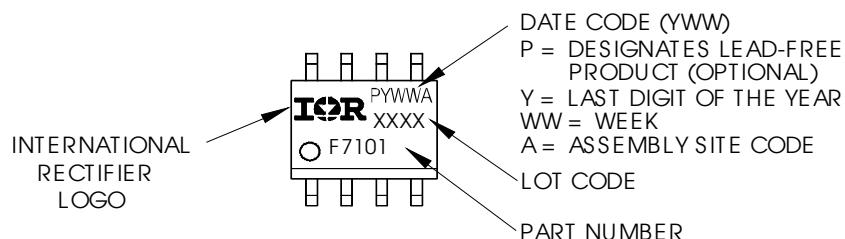


FOOTPRINT



SO-8 Part Marking

EXAMPLE: THIS IS AN IRF7101 (MOSFET)



Notes:

1. For an Automotive Qualified version of this part please see: <http://www.irf.com/product-info/auto/>
2. For the most current drawing please refer to IR website at <http://www.irf.com/package/>

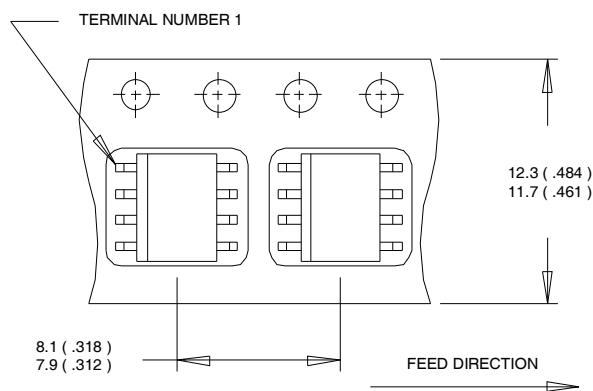
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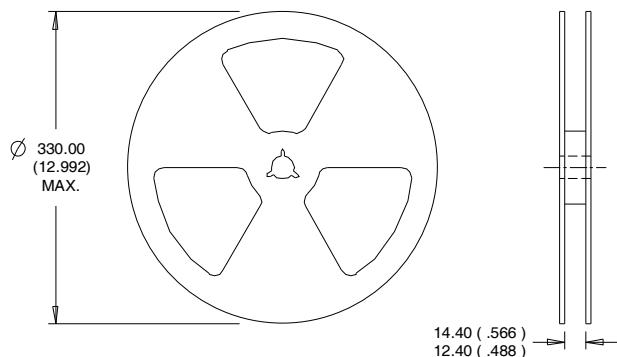
SO-8 Tape and Reel

Dimensions are shown in millimeters (inches)



NOTES:

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

For the most current drawing please refer to IR website at <http://www.irf.com/package/>

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Qualification Information[†]

Qualification level	Industrial [†]	
	(per JEDEC JESD47F ^{††} guidelines)	
Moisture Sensitivity Level	SO-8	MSL1 (per JEDEC J-STD-020D ^{††})
RoHS Compliant	Yes	

† Qualification standards can be found at International Rectifier's web site
<http://www.irf.com/product-info/reliability>

†† Applicable version of JEDEC standard at the time of product release.

Revision History

Date	Comments
10/3/2014	• Added ordering information to reflect the End-Of-life

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IR WORLD HEADQUARTERS: 101 N. Sepulveda Blvd., El Segundo, California 90245, USA
To contact International Rectifier, please visit <http://www.irf.com/whoto-call/>